P/N 152611

Specifications

Machined Dip Sockets Series:

BU

Ratings:

Current	1A max.
Voltage	10 mV - 60 V
Dielectric strength	> 1000 V (RMS)
Contact resistance	≤ 7 mΩ
Insulation resistance	> 10^{12}Ω
Air and creepage distance	> 0.6 mm
PCB thickness:	1.6 mm - 2.0 mm
PCB hole size:	.7 mm - .9 mm

Material:

Plastic	PBT Glass-filled, UL94V-0
Sleeve	Turned brass, Flash copper plated, Nickel 2-3µm, Tin 5µm
Clip	Beryllium-copper, Nickel 2-3µm, Gold 0.25µm
Temperature range	-55°C / +125°C, 260°C for 5 sec. (solder bath resistant)
Insertion depth	2.4 mm min. - 3.9 mm max.
Insertion diameter	0.4 mm min. - 0.56 mm max.
Mechanical life	100 cycles

ORDERING PROCEDURE

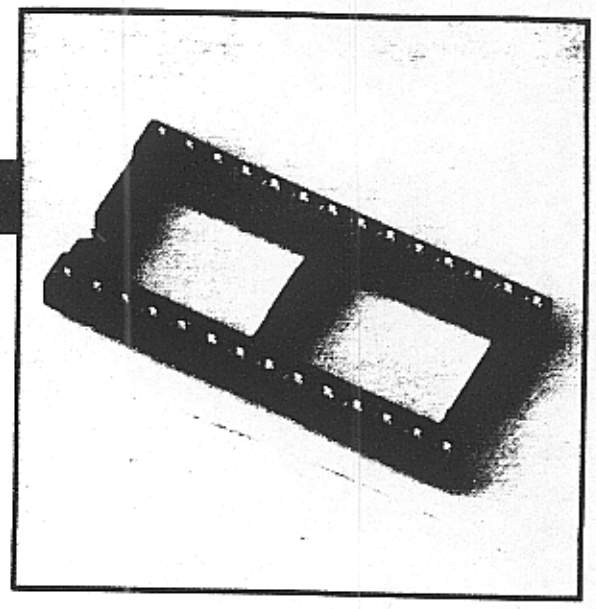
1 - 2 3 4 - 5

1) Series
2) Number of Positions (see chart for available positions)
3) Contact style:
   O = Solder tail
4) Plating:
   Z = Gold clip / Tin sleeve
   G = Gold clip / Gold sleeve
5) Series options:
   SFD = Ultra low profile
   178HT = Surface mount
   CA = Capacitor

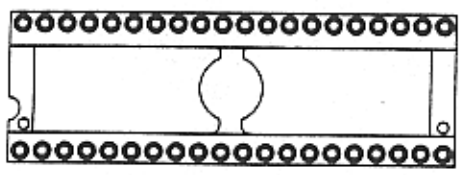
Please refer to following pages for ordering examples.

Series: BU-178HT

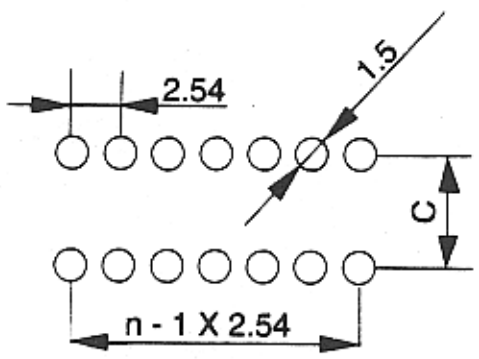
SMT Machined Dip Socket



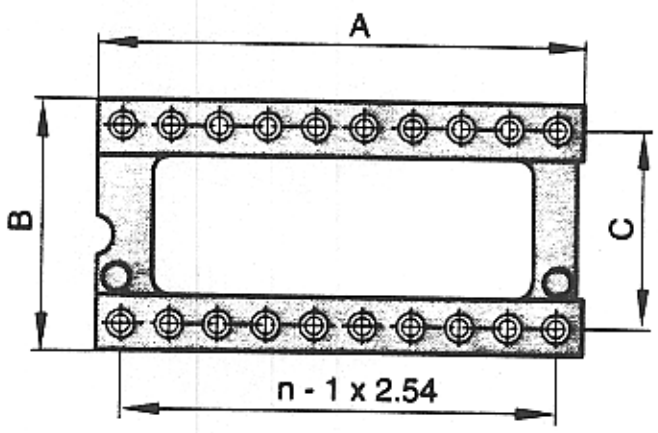
- ❖ Insertion diameter, .40 mm min. - .56 mm max.
- ❖ Insertion depth, 2.4 mm min. - 3.8 mm max.
- ❖ Process temperature, 260°C for 10 sec. / 215°C for 2 minutes
- ❖ Four finger clip with funnel design entry
- ❖ Side and end stackable
- ❖ Pin 1 polarized

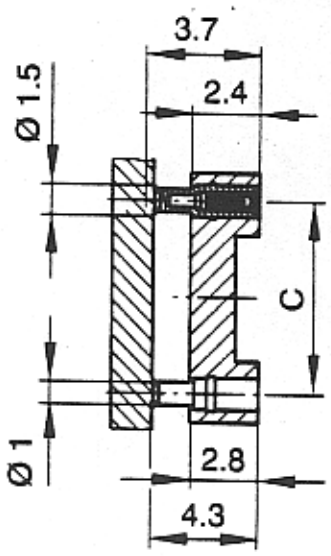


OPTIONAL PICK AND PLACE PAD



RECOMMENDED PCB LAYOUT





Ordering example: BU - 14 0 Z - 178HT

Positions	A	B	C
04	5.08	10.08	7.62
06	7.62	10.08	7.62
08	10.16	10.08	7.62
10	12.70	10.08	7.62
14	17.78	10.08	7.62
16	20.32	10.08	7.62
18	22.86	10.08	7.62
20	25.40	10.08	7.62
22	27.94	10.08	15.24
22*	27.94	10.08	7.62

Positions	A	B	C
24	30.48	17.70	15.24
24*	30.48	10.08	7.62
28	35.56	10.08	15.24
28*	35.56	10.08	7.62
32	40.64	17.70	15.24
36	45.75	17.70	15.24
40	50.80	17.70	15.24
48	60.96	17.70	15.24
50	63.50	25.32	22.86
64	81.28	25.32	22.86

*Add 1 for 7.62 spacing on 22(1), 24(1) and 28(1) positions